

RoHS

COMPLIANT HALOGEN

FREE

N-Channel 20 V (D-S) MOSFET

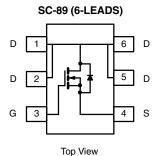
PRODUCT SUMMARY				
V _{DS} (V)	R _{DS(on)} (Ω) I _D (A)		Q _g (Typ.)	
	0.089 at V _{GS} = 4.5 V	1.32		
20	0.098 at V _{GS} = 2.5 V	1.26	5.2	
	0.121 at V _{GS} = 1.8 V	1.13		

FEATURES

- Halogen-free According to IEC 61249-2-21
 Definition
- TrenchFET[®] Power MOSFET
- 100 % R_g Tested
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

Load Switch for Portable Devices



Marking Code

Ordering Information: Si1056X-T1-GE3 (Lead (Pb)-free and Halogen-free)

Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	20	V	
Gate-Source Voltage		V _{GS}	± 8	v	
Continuous Drain Current (T _J = 150 °C) ^a	T _A = 25 °C	1-	1.32 ^{b, c}		
	T _A = 70 °C	I _D	1.05 ^{b, c}	A	
Pulsed Drain Current		I _{DM}	6	A	
Avalanche Current	L = 0.1 mH	I _{AS}	8		
Repetitive Avalanche Energy	L = 0.1 mm	E _{AS}	3.2	mJ	
Continuous Source-Drain Diode Current	T _A = 25 °C	ا _S	0.2 ^{b, c}	A	
Maximum Davier Dissignational	T _A = 25 °C	P _D	0.236 ^{b, c}	w	
Maximum Power Dissipation ^a	T _A = 70 °C	' D	0.151 ^{b, c}	VV	
Operating Junction and Storage Temperature Ra	T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{b, d}	t ≤ 5 s	R _{thJA}	440	530	°C/W	
	Steady State		540	650	0/11	

Notes:

a. Based on T_C = 25 °C.

b. Surface mounted on 1" x 1" FR4 board.

c. t = 5 s.

d. Maximum under steady state conditions is 650 °C/W.

Si1056X

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_D = 250 \mu A$	20			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		18.2		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	- iD = 200 μA		- 2.71			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \ \mu A$	0.35		0.95	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 8 V$			± 100	nA	
	I _{DSS}	V _{DS} = 20 V, V _{GS} = 0 V			1	μΑ	
Zero Gate Voltage Drain Current		$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 85 ^{\circ}\text{C}$			10		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} = \ge 5 V, V_{GS} = 4.5 V$	6			Α	
Drain-Source On-State Resistance ^a		V _{GS} = 4.5 V, I _D = 1.32 A		0.074	0.089		
	R _{DS(on)}	V _{GS} = 2.5 V, I _D = 1.26 A		0.082	0.098	Ω	
		V _{GS} = 1.8 V, I _D = 1.13 A		0.093	0.121		
Forward Transconductance	9 _{fs}	V _{DS} = 10 V, I _D = 1.32 A		7.5		S	
Dynamic ^b							
Input Capacitance	C _{iss}			400		pF	
Output Capacitance	C _{oss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz		70			
Reverse Transfer Capacitance	C _{rss}			40			
		V _{DS} = 10 V, V _{GS} = 5 V, I _D = 1.32 A		5.8	8.7		
Total Gate Charge	Q_g			5.2	7.8		
Gate-Source Charge	Q _{gs}	V _{DS} = 10 V, V _{GS} = 4.5 V, I _D = 1.32 A		0.83		nC	
Gate-Drain Charge	Q _{gd}			0.71			
Gate Resistance	R _g	f = 1 MHz		3.8	5.7	Ω	
Turn-On Delay Time	t _{d(on)}			6.8	10.2		
Rise Time t _r		$V_{DD} = 10 \text{ V}, \text{ R}_{1} = 9.52 \Omega$		19	28.5		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 1.05 \text{ A}, \text{ V}_{\text{GEN}} = 4.5 \text{ V}, \text{ R}_{\text{a}} = 1 \Omega$		18	27	ns	
Fall Time	t _f			6	9		
Drain-Source Body Diode Characterist	ics						
Pulse Diode Forward Current ^a	I _{SM}				6	А	
Body Diode Voltage	V _{SD}	I _S = 1.0 A		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			10.0	15	nC	
Body Diode Reverse Recovery Charge	Q _{rr}	1	L	3.5	5.3	ns	
Reverse Recovery Fall Time	t _a	I _F = 1.0 A, dI/dt = 100 A/μs		6.6	-		
Reverse Recovery Rise Time	t _b	1		3.4			

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

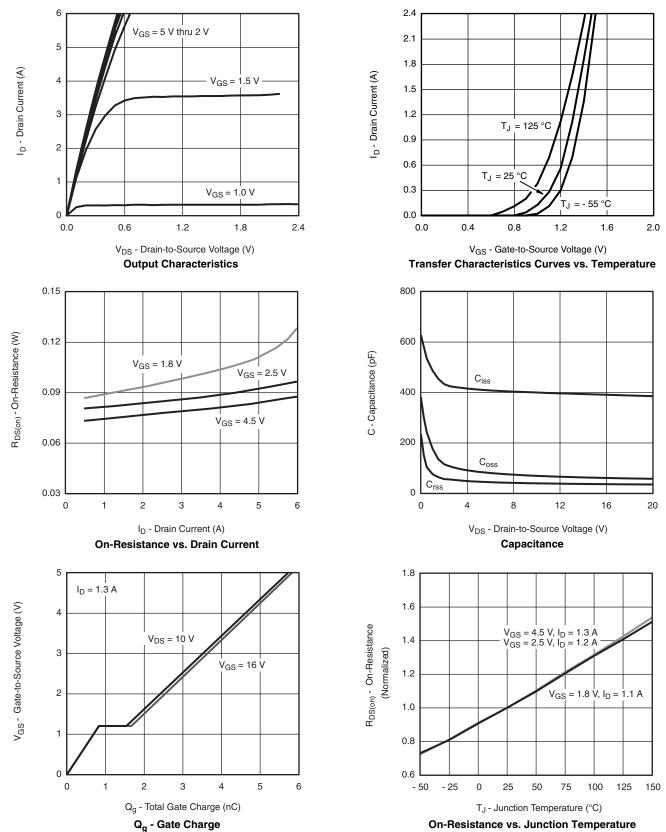
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



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TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)

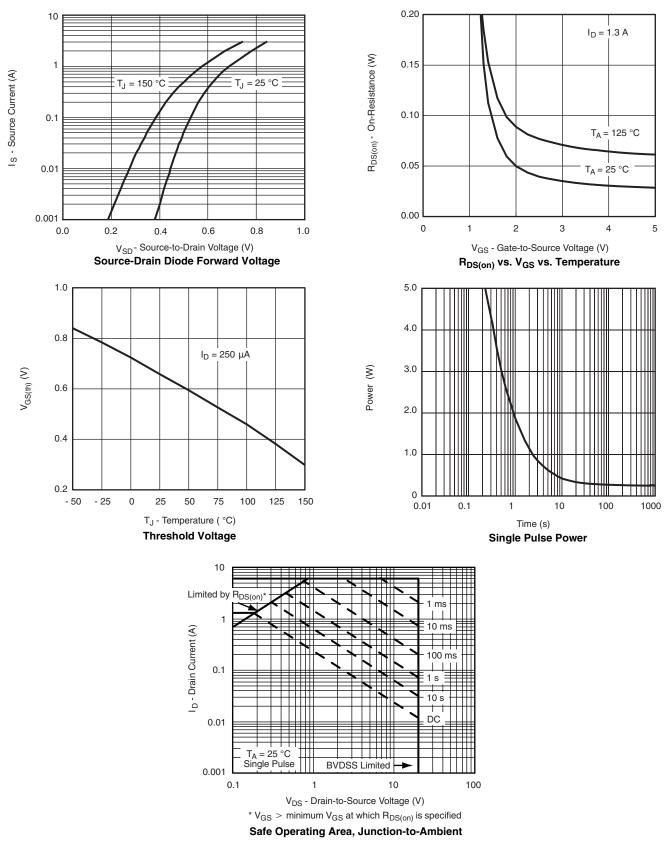


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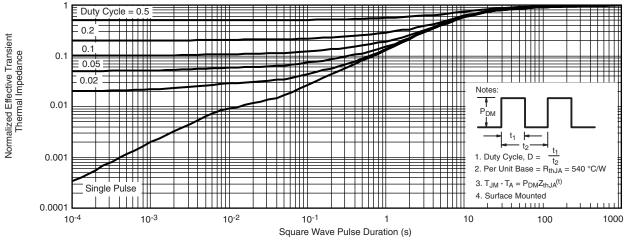


TYPICAL CHARACTERISTICS ($T_A = 25 \text{ °C}$, unless otherwise noted)





TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient

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